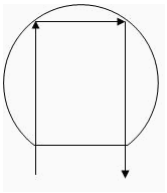
Part Number	Customer

Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	150.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110} +/- 0.4 degree	Wafer Vendor. PFO tolerance nominally 0.25 ~ 0.4deg.
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	None	Wafer Vendor
	5.0	Overall Thickness	500.00 +/- 5.00 µm	ADE, 100%
	6.0	Total Thickness Variation (TTV)	<3.00µm	Guaranteed by Process
	7.0	Bow	<40.00µm	Estimate Bulk DSP silicon. ADE to ASTM F534, 100%
	8.0	Warp	<40.00µm	Estimate Bulk DSP silicon.
	9.0	Edge Chips	0	Bright Light, 100% (note 2)
	10.0	Edge Exclusion	5mm	
	11.0	Frontsurface condition	Polished with Thermal Oxide	Bright Light, 100% (note2)
HandleSilicon	12.0	Handle Growth Method	CZ/MCZ	Wafer Vendor
	13.0	Handle Orientation	{100} +/- 0.2 degree	Wafer Vendor
	14.0	Handle Thickness	500.00 +/- 5.00 µm	ADE, 100%
	15.0	Handle Doping Type	N	Wafer Vendor
	16.0	Handle Dopant	Phosphorous	Wafer Vendor
	17.0	Handle Resistivity	1 ~ 20 Ohmcm	Wafer Vendor
	18.0	Handle Oxygen Concentration	<13 ppma	Wafer Vendor
	19.0	Backside Finish	Polished with oxide, light handling marks and lasermark	
	20.0	Total scratch length	<10mm total length	Bright Light, 100% (note 2)
	21.0	Surface Haze	None	Bright Light, 100% (note 2)
	22.0	Handle Pad Oxide	10,000.00 +/- 1,000.00 A	Nanospec centre point, 4%

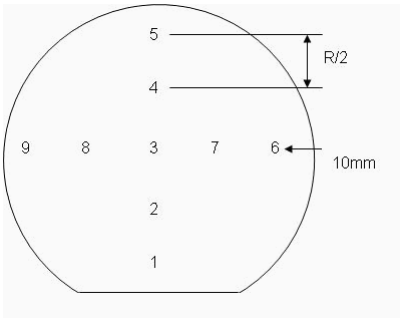
Part Number	Customer

Category	Parameter	Specification	Measurement Method
Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.		



2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information